SIS - Standardiseringskommissionen i Sverige

SVENSK STANDARD SS-ISO 9455-11

Handläggande organ	Fastställd	Utgåva	Sida
MATERIALNORMCENTRALEN	1994-01-21	1	1 (1 + 3)

Fluss för mjuklödning — Provningsmetoder — Del 11: Löslighet hos flussrester

Soft soldering fluxes — Test methods — Part 11: Solubility of flux residues

Den internationella standarden ISO 9455-11:1991 gäller som svensk standard.

Detta dokument innehåller den officiella engelska versionen av ISO 9455-11:1991.

Standarder kan beställas hos SIS som även lämnar allmänna upplysningar om svensk och utländsk standard.
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Soft soldering fluxes — Test methods —

Part 11:
Solubility of flux residues

1 Scope

This part of ISO 9455 specifies a qualitative method for assessing the solubility of flux residues in a selected solvent. The method is applicable to all fluxes of Type 1, as defined in ISO 9454-1.

NOTE 1 This test gives no assurance that post-cleaning residues, which may be present in sufficiently small amounts to pass the test, will not be detrimental to the soldered assembly in the long term.

2 Normative references

The following standards contain provisions which, through reference in this text, constitute provisions of this part of ISO 9455. At the time of publication, the editions indicated were valid. All standards are subject to revision, and parties to agreements based on this part of ISO 9455 are encouraged to investigate the possibility of applying the most recent editions of the standards indicated below. Members of IEC and ISO maintain registers of currently valid International Standards.

ISO 1634-1:1987, *Wrought copper and copper alloy plate, sheet and strip — Part 1: Technical conditions of delivery for plate, sheet and strip for general purposes.*

ISO 9454-1:1990, *Soft soldering fluxes — Classification and requirements — Part 1: Classification, labelling and packaging.*

3 Principle

A brass test plate is fluxed, heated to soldering temperature and, after conditioning, is immersed in the selected solvent to dissolve the flux residue. The effectiveness of the flux residue removal is indicated by the presence of a current flowing across the junction between the cleaned area and an electrical probe tip.

4 Reagents and materials

4.1 General

In the test use only reagents of recognized analytical quality and only distilled, or deionized, water.

4.2 Acid cleaning solution

Add cautiously, with stirring, 75 ml of sulfuric acid (ϱ 1,84 g/ml) to 210 ml of water and mix. Cool, add 15 ml of nitric acid (ϱ 1,42 g/ml) and mix the solution thoroughly.

4.3 Solvent

This is the solvent selected for the flux residue removal as recommended by the flux manufacturer or supplier.

NOTE 2 The solvent to be used will vary with the flux composition.

4.4 Industrial methylated spirits.

4.5 Oil crayon.

4.6 Brass test plates, each 60 mm x 60 mm, cut from 0,5 mm thick brass sheet complying with ISO 1634-1, alloy CuZn 37, condition HA.

A 3 mm deep depression shall be formed in the centre of each test plate by means of a 20 mm diameter steel ball.